

COMPLIANT HALOGEN

FREE

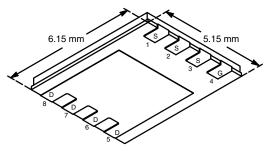
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Vishay Siliconix

N-Channel Reduced Q_g, Fast Switching MOSFET

PRODUCT	RODUCT SUMMARY			
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A)		
30	0.00975 at V _{GS} = 10 V	15		
30	0.01375 at V _{GS} = 4.5 V	13		

PowerPAK SO-8



Bottom View

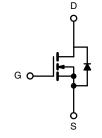
Ordering Information: Si7392DP-T1-E3 (Lead (Pb)-free) Si7392DP-T1-GE3 (Lead (Pb)-free and Halogen-free)

FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- Extremely Low Q_{gd} for Low Switching Losses TrenchFET[®] Power MOSFET RoHS
- New Low Thermal Resistance PowerPAK[®] Package with Low 1.07 mm Profile
- 100 % R_g Tested
- 100 % UIS Tested
- Complaint to RoHS Directive 2002/95/EC

APPLICATIONS

- High-Side DC/DC Conversion
 - Notebook - Server



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	$(T_A = 25 \ ^{\circ}C, unle$	ess otherwise	noted)		
Parameter		Symbol	10 s	Steady State	Unit
Drain-Source Voltage		V _{DS}	30		V
Gate-Source Voltage		V _{GS}	± 20		
Continuous Drain Current /T 150 °C\a	T _A = 25 °C	- I _D	15	9	
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 70 °C		12	7	
Pulsed Drain Current		I _{DM}	± 50		А
Continuous Source Current (Diode Conduction) ^a		۱ _S	4.1	1.5	
Avalanche Current	L = 0.1 mH	I _{AS} 30			
Single-Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	45		mJ
	T _A = 25 °C	P _D	5	1.8	W
Maximum Power Dissipation ^a	T _A = 70 °C		3.2	1.1	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150		℃
Soldering Recommendations (Peak Temperature) ^{b, c}			260		30

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
	t ≤ 10 s	R _{thJA}	20	25	
Maximum Junction-to-Ambient (MOSFET) ^a	Steady State		53	70	°C/W
Maximum Junction-to-Case (Drain)	Steady State	R _{thJC}	3.5	4.5	

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. See solder profile (www.vishay.com/ppg?73257). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.

c. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.

* Pb containing terminations are not RoHS compliant, exemptions may apply.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	1.0		3.0	V
Gate-Body Leakage	I _{GSS}				± 100	nA
Zava Cata Valtaga Drain Current		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$		1		
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 70 ^{\circ}\text{C}$			5	μA
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	40			Α
		V _{GS} = 10 V, I _D = 15 A		0.008	0.00975	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 13 \text{ A}$		0.011	0.01375	Ω
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 15 A		40		S
Diode Forward Voltage ^a	V _{SD}	I _S = 4.1 A, V _{GS} = 0 V		0.75	1.1	V
Dynamic ^b				•		
Total Gate Charge	Qg			10	15	
Gate-Source Charge	Q _{gs}	$V_{DS} = 15 \text{ V}, \text{ V}_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 15 \text{ A}$		3.5		nC
Gate-Drain Charge	Q _{gd}			2.6		
Gate Resistance	R _g			1.6	2.7	Ω
Turn-On Delay Time	t _{d(on)}			15	25	
Rise Time	t _r	V_{DD} = 15 V, R_L = 15 Ω		7	15	
Turn-Off Delay Time	t _{d(off)}	$\text{I}_\text{D}\cong \text{1}$ A, $\text{V}_\text{GEN}=\text{10}$ V, $\text{R}_\text{g}=\text{6}~\Omega$		46	70	ns
Fall Time	t _f			9	17	
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 2.7 A, dI/dt = 100 A/μs		30	60	

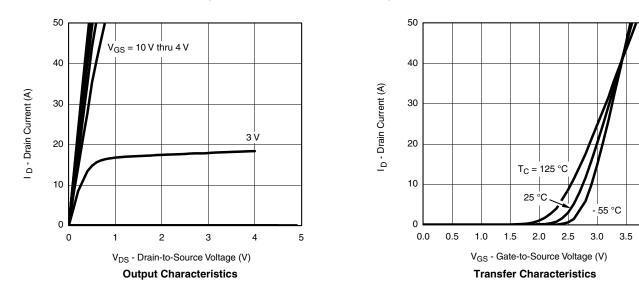
Notes:

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



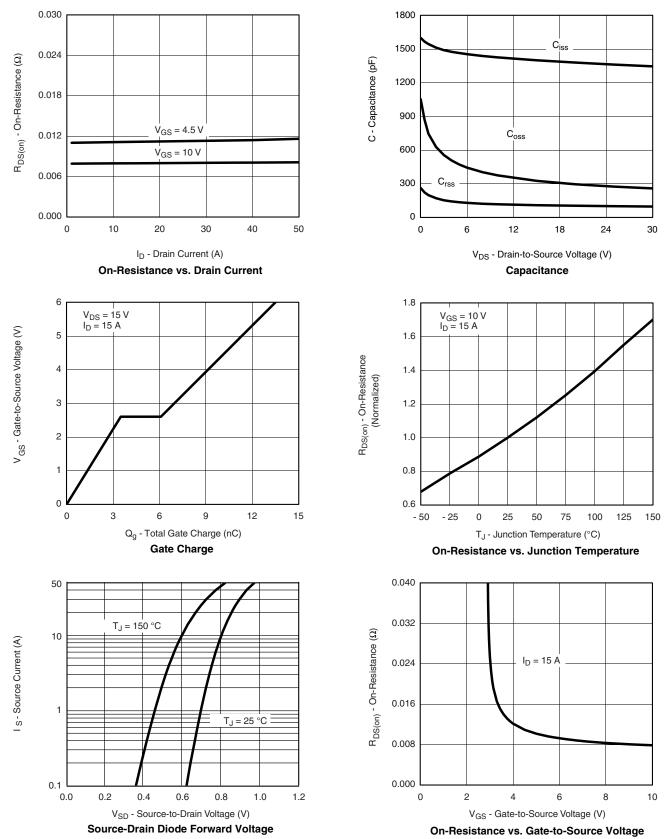
4.0



Si7392DP

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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



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Si7392DP

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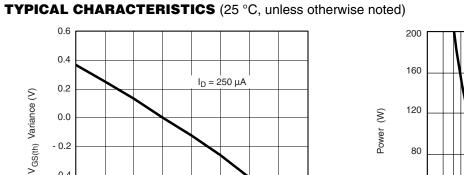
0.0

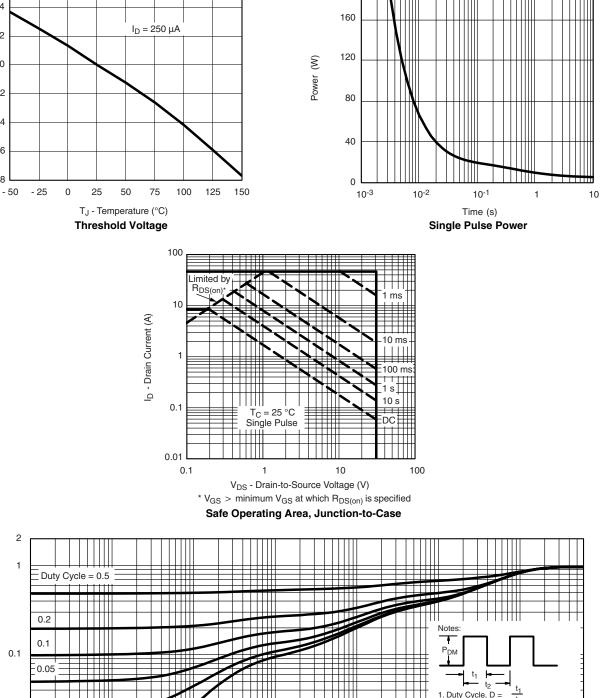
- 0.2

- 0.4

- 0.6

- 0.8





1. Duty Cycle, D = 1. Duty Cycle, D = $\frac{t_2}{t_2}$ 2. Per Unit Base = R_{thJA} = 125 °C/W 0.02 Tt 3. T_{JM} - $T_A = P_{DM}Z_{thJA}^{(t)}$ Single Pulse 4. Surface Mounted 0.01 10-4 10⁻³ 10-10⁻¹ 1 10 100 600 Square Wave Pulse Duration (s) Normalized Thermal Transient Impedance, Junction-to-Ambient

Normalized Effective Transient Thermal Impedance

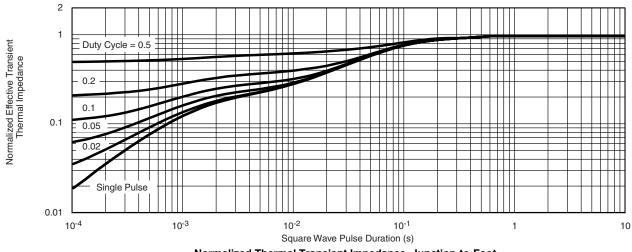




Si7392DP

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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?72165.



Vishay Siliconix

PowerPAK[®] SO-8, (Single/Dual)









Backside View of Dual Pad

Notes

1. Inch will govern.

2 Dimensions exclusive of mold gate burrs.

3. Dimensions exclusive of mold flash and cutting burrs.

DIM.		MILLIMETERS		INCHES			
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
A	0.97	1.04	1.12	0.038	0.041	0.044	
A1		-	0.05	0	-	0.002	
b	0.33	0.41	0.51	0.013	0.016	0.020	
С	0.23	0.28	0.33	0.009	0.011	0.013	
D	5.05	5.15	5.26	0.199	0.203	0.207	
D1	4.80	4.90	5.00	0.189	0.193	0.197	
D2	3.56	3.76	3.91	0.140	0.148	0.154	
D3	1.32	1.50	1.68	0.052	0.059	0.066	
D4	0.57 typ.				0.0225 typ.		
D5		3.98 typ.			0.157 typ.		
E	6.05	6.15	6.25	0.238	0.242	0.246	
E1	5.79	5.89	5.99	0.228	0.232	0.236	
E2 (for AL product)	3.30	3.48	3.66	0.130	0.137	0.144	
E2 (for other product)	3.48	3.66	3.84	0.137	0.144	0.151	
E3	3.68	3.78	3.91	0.145	0.149	0.154	
E4 (for AL product)		0.58 typ.		0.023 typ.			
E4 (for other product)		0.75 typ.		0.030 typ.			
е	1.27 BSC			0.050 BSC			
K (for AL product)	1.45 typ.			0.057 typ.			
K (for other product)	1.27 typ.			0.050 typ.			
K1	0.56	-	-	0.022	-	-	
Н	0.51	0.61	0.71	0.020	0.024	0.028	
L	0.51	0.61	0.71	0.020	0.024	0.028	
L1	0.06	0.13	0.20	0.002	0.005	0.008	
θ	0°	-	12°	0°	-	12°	
W	0.15	0.25	0.36	0.006	0.010	0.014	
М	0.125 typ.			0.005 typ.			

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Application Note 826

Vishay Siliconix

RECOMMENDED MINIMUM PADS FOR PowerPAK® SO-8 Single



Recommended Minimum Pads Dimensions in Inches/(mm)

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